



The following material specifications are available:

Mark	Materials	Dimension	Surface qualities	Material No.
A	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Plain - lamination quality (standard degreased)	145547
B	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Plain - electrolytically degreased (enhanced degreasing)	145546
D	High Tensile Copper Alloy HTA-520	0.010 x 250 mm	Plain - lamination quality (standard degreased)	148050
E	High Tensile Copper Alloy HTA-520	0.010 x 250 mm	Plain - electrolytically degreased (enhanced degreasing)	148051
J	High Tensile Copper Alloy HTA-750	0.010 x 250 mm	Plain - lamination quality (standard degreased)	153143
K	High Tensile Copper Alloy HTA-750	0.010 x 250 mm	Plain - electrolytically degreased (enhanced degreasing)	153144
M	High Tensile Copper Alloy HTA-600	0.010 x 250 mm	Plain - lamination quality (standard degreased)	159338
N	High Tensile Copper Alloy HTA-600	0.010 x 250 mm	Plain - electrolytically degreased (enhanced degreasing)	159339
O	Tin clad Copper SE-Cu Copper	0.010 x 250 mm	Tin clad on both sides with Sn 100 - hard as rolled	160833
F	Nickel 99.6 (N201)	0.010 x 250 mm	Plain - lamination quality (standard degreased)	158954
G	Nickel 99.6 (N201)	0.010 x 250 mm	Plain - electrolytically degreased (enhanced degreasing)	159611

RELATED PRODUCTS

Please consider also our material for bipolar electrode application and tab ribbon:

- **Aluminum Copper-Clad material** used for tab ribbon and bipolar electrode application and
- **Tab Ribbon** made from Copper, Silver, Nickel and their alloys

For further information please visit our website: www.schlenk.com or contact our Area Sales Manager or your local representative. E-Mail contact: battery@schlenk.com